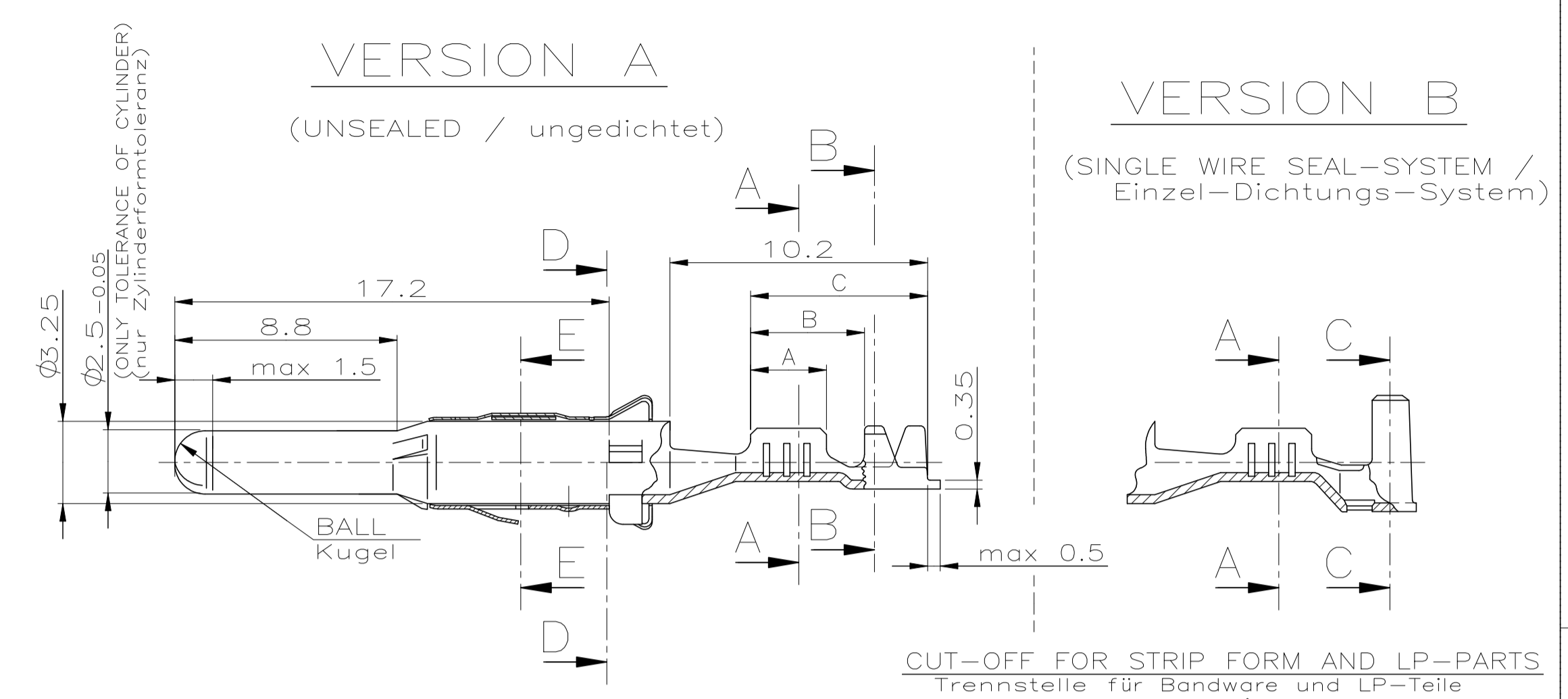
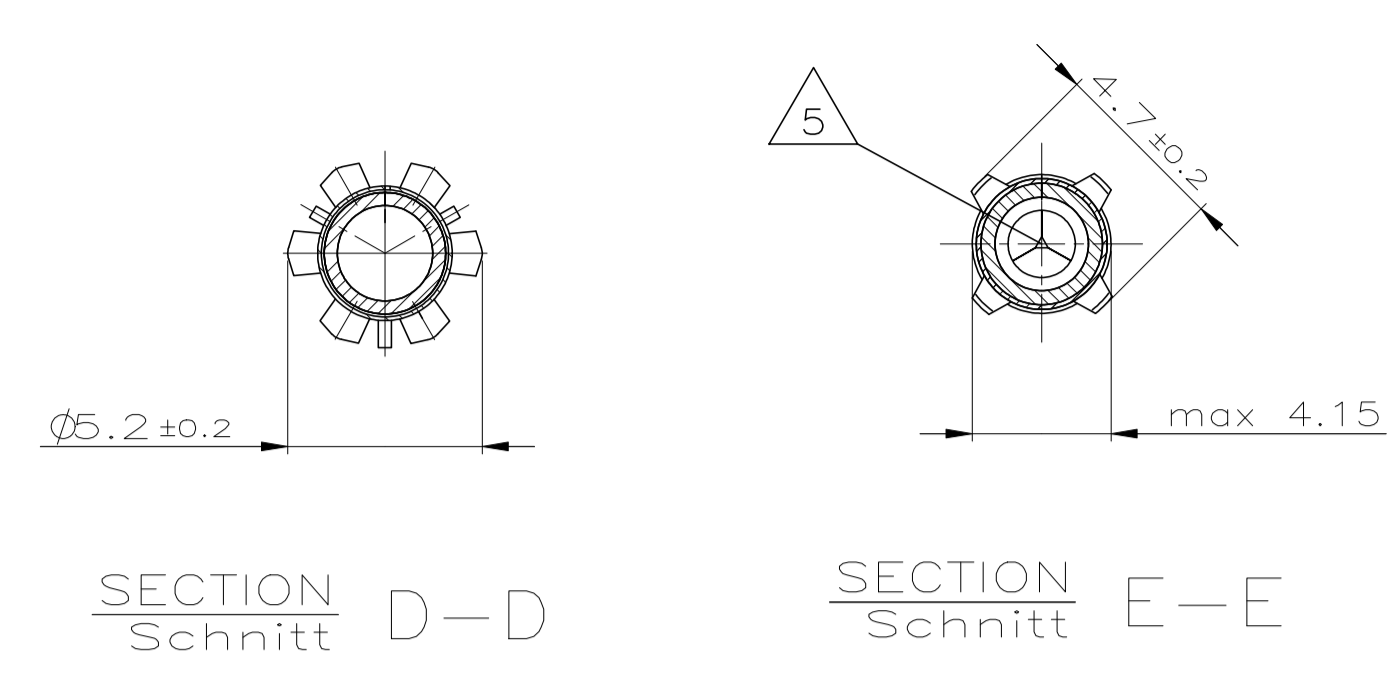


LOC	DIST	REV	DESCRIPTION	DATE	DM	APD
AI	-	A4	REVISED PER ECR-11-025934	28DEC11	RK	HMR
		A5	E-23-173042	20APR2023	SH	MC



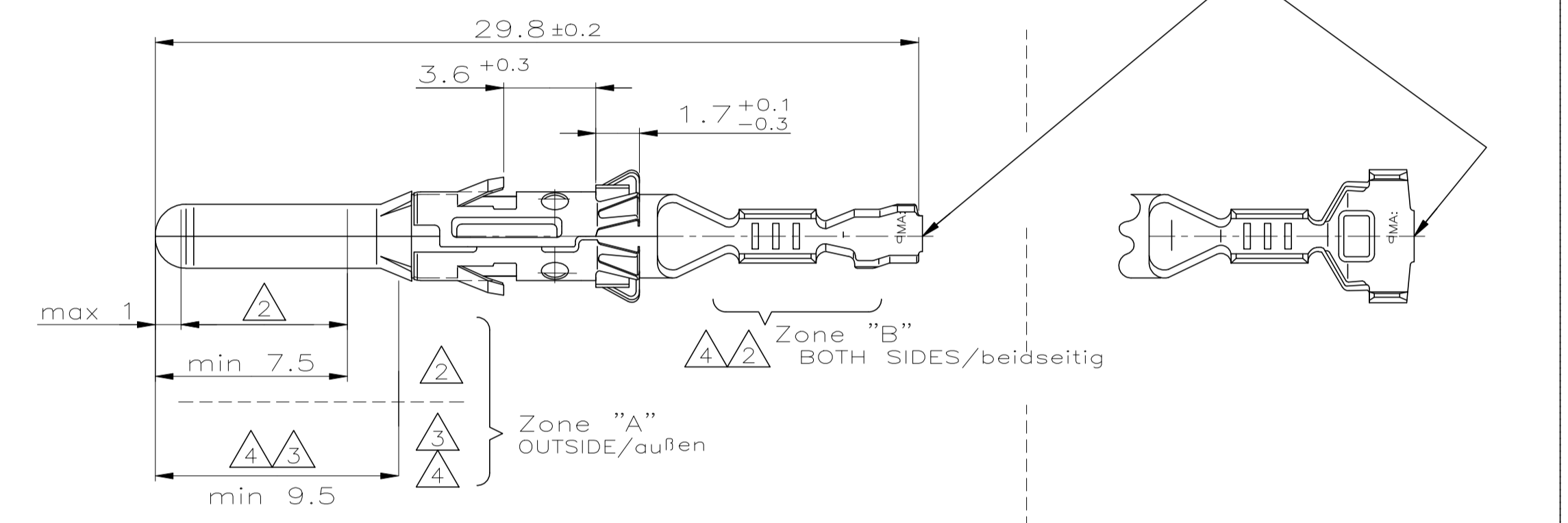
Version B (SINGLE WIRE SEAL-SYSTEM / Einzel-Dichtungs-System)

TE CONNECTIVITY ORDER-Nr.	TE CONNECTIVITY ORDER-Nr.	MATERIAL	SURFACE	DGB [mm ²]	WIRE CRIMP Drahtcrimp	NSUL.-CRIMP Isol.-Crimp	WIRE CRIMP HEIGHT CH Drahtcrimp-Höhe CH	APPLICATION TOOL Anschlag-WKZ	HAND TOOL Handzange	A	B	C	TE CONNECTIVITY ORDER-Nr. SINGLE SEAL Einzeldichtung	TE CONNECTIVITY ORDER-Nr. DEAD END PLUG Blindstopfen	
1-962800-4	1-962973-4	CuNiSi	FLR	>2.5-4.0	E = 4.3	H = 5.4	4.0mm ² = 2.30	MQC-Applicator		4	6.9	8.5	828985-1	-	
962800-7	962973-7				G = 4.5	K = 5.9	3.0mm ² = 2.05	4151297-X							
962800-1	962973-1				D _{cr} = 2.4	D = 3.9	3.0mm ² = 2.05								
1-929968-4	1-962972-4	CuNiSi	FLR	>1.0-2.5	E = 3.6	H = 5.0	2.5mm ² = 1.97	MQC-Applicator	539679-2	4	6.9	8.5	828921-1	828922-1	
929968-8	962972-8				G = 3.8	K = 5.0	2.0mm ² = 1.82	2-878486-2	1579024-5						
929968-1	962972-1				D _{cr} = 1.7	D = 3.6	1.5mm ² = 1.67	2151345							
1-929967-4	1-962971-4	CuNiSi	FLR	0.5-1.0	E = 2.6	H = 4.8	1.0mm ² = 1.45	MQC-Applicator	734289-1	3	5.4	7	828920-1	828922-1	
929967-8	962971-8				G = 2.8	K = 4.8	0.75mm ² = 1.36	2-878485-2	1579024-3						
929967-1	962971-1				D _{cr} = 1.1	D = 3.2	0.5mm ² = 1.27	2151139							
1-929966-4	1-962970-4	CuNiSi	FLR	0.2-0.4	E = 2.1	H = 4.5	0.35mm ² = 1.11	MQC-Applicator	734289-1	3	5.4	7	828920-1	828922-1	
929966-8	962970-8				G = 2.1	K = 4.5	0.35mm ² = 1.11	2-878484-2	1579024-3						
929966-1	962970-1				D _{cr} = 0.8	D = 3.2	0.35mm ² = 1.11	2151732							

TE CONNECTIVITY ORDER-Nr. STRIP FORM Bandware	TE CONNECTIVITY ORDER-Nr. LOOSE PIECE Einzelausführung	MATERIAL Werkstoff	SURFACE Oberfläche	DGB [mm ²]	WIRE CRIMP Drahtcrimp	NSUL.-CRIMP Isol.-Crimp	WIRE CRIMP HEIGHT CH Drahtcrimp-Höhe CH	APPLICATION TOOL Anschlag-WKZ	HAND TOOL Handzange	A	B	C
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TE CONNECTIVITY ORDER-Nr.	TE CONNECTIVITY ORDER-Nr.	MATERIAL	SURFACE	DGB [mm ²]	WIRE CRIMP Drahtcrimp	NSUL.-CRIMP Isol.-Crimp	WIRE CRIMP HEIGHT CH Drahtcrimp-Höhe CH	APPLICATION TOOL Anschlag-WKZ	HAND TOOL Handzange	A	B	C	
1-929965-4	1-962969-4	CuNiSi	FLR	>2.5-4.0	E = 4.3	H = 5.4	4.0mm ² = 2.30	MQC-Applicator	734285-3	4	5.5	8.5	
929965-8	962969-8				G = 4.5	K = 5.6	3.0mm ² = 2.05	2-878483-2	2836098	734289-3			
929965-1	962969-1				D _{cr} = 2.4	D = 3.2	3.0mm ² = 2.05						
1-929964-4	1-962968-4	CuNiSi	FLR	>1.0-2.5	E = 3.6	H = 4.3	2.5mm ² = 1.97	MQC-Applicator	734285-2	4	5.5	8.5	
929964-8	962968-8				G = 3.8	K = 4.5	2.0mm ² = 1.82	2-878482-2	2266503				
929964-1	962968-1				D _{cr} = 1.7	D = 2.6	1.25mm ² = 1.60						
1-929963-4	1-962967-4	CuNiSi	FLR	0.5-1.0	E = 2.6	H = 3.2	1.0mm ² = 1.45	MQC-Applicator	734285-1	3	4.5	7	
929963-8	962967-8				G = 2.8	K = 3.4	0.75mm ² = 1.36	2-878481-2	2266254	2-1579024-5			
929963-1	962967-1				D _{cr} = 1.1	D = 1.8	0.5mm ² = 1.27						
1-929962-4	1-962966-4	CuNiSi	FLR	0.2-0.4	E = 2.1	H = 2.5	0.35mm ² = 1.11	MQC-Applicator	734285-1	3	4.5	7	
929962-8	962966-8				G = 2.1	K = 2.5	0.25mm ² = 1.07	2-878480-2	2836097	2-1579024-4			
929962-1	962966-1				D _{cr} = 0.8	D = 1.4	0.2mm ² = 1.05						

TE CONNECTIVITY ORDER-Nr. STRIP FORM Bandware	TE CONNECTIVITY ORDER-Nr. LOOSE PIECE Einzelausführung	MATERIAL Werkstoff	SURFACE Oberfläche	DGB [mm ²]	WIRE CRIMP Drahtcrimp	NSUL.-CRIMP Isol.-Crimp	WIRE CRIMP HEIGHT CH Drahtcrimp-Höhe CH	APPLICATION TOOL Anschlag-WKZ	HAND TOOL Handzange	A	B	C
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- REMARKS**
Bemerkungen
- 1 **PRE TINNED** 1-2µm
vorverzinnt
 - 2 **ZONE "A": MIN 0.8µm ELECTROPL. Au OVER MIN 1.3µm ELECTROPL. Ni LAYER**
min 0.8µm galv. Au über min 1.3µm galv. Ni
ZONE "B": 1-2µm ELECTROPL. Sn OVER MIN 0.1µm ELECTROPL. Ni
1-2µm galv. Sn über min 0.1µm galv. Ni
REST: min 0.1µm ELECTROPL. Ni
min 0.1µm galv. Ni
 - 3 **ZONE "A": MIN 3µm ELECTROPL. Ag**
min 3µm galv. Ag
REST: min 0.5µm ELECTROPL. Ag
min 0.5µm galv. Ag
 - 4 **ZONE "A": MIN 3µm ELECTROPL. Ag**
min 3µm galv. Ag
ZONE "B": 1-3µm ELECTROPL. Sn
1-3µm galv. Sn
REST: SILVER OR TIN ALLOWED IN TRANSITION AREAS.OVERLAPPING LAYERS AND PLAIN SURFACES ARE NOT ALLOWED.
Silber oder Zinn im Übergangsbereich erlaubt.
überlagernde Schichten oder blanke Stellen sind nicht erlaubt.
 - 5 **AT AREA OF TOP OPENING PERMITTED**
Im Bereich der Spitze Öffnung zulässig
 - 6 **AVAILABILITY MUST BE CHECKED BY TE CONNECTIVITY**
Verfügbarkeit ist von TE CONNECTIVITY zu prüfen

THIS DRAWING IS A CONTROLLED DOCUMENT. DIESE ZEICHNUNG IST EIN KONTROLLIERTES DOKUMENT.

DM: C. Goetz, 25-JUN-2001
CHK: J. Granzow, 25-JUN-2001

STE TE Connectivity

PRODUCT SPEC: 108-18027
APPLICATION SPEC: 114-18020

SCALE: MASSSTAB 5:1
SHEET: 1 OF 1
REV: A5